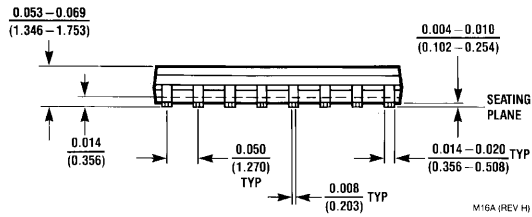
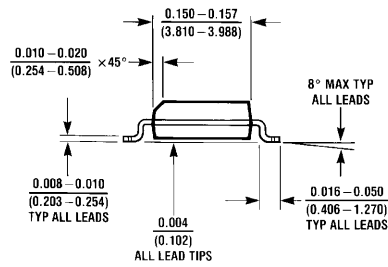
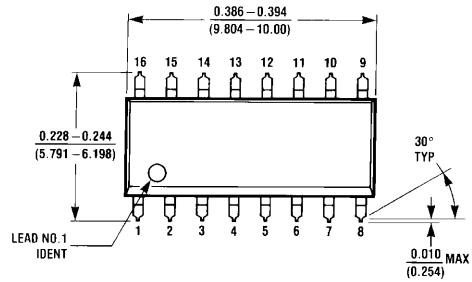




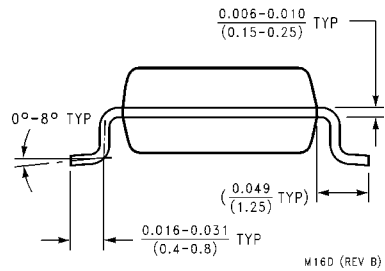
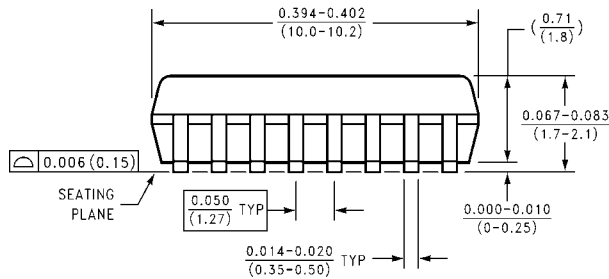
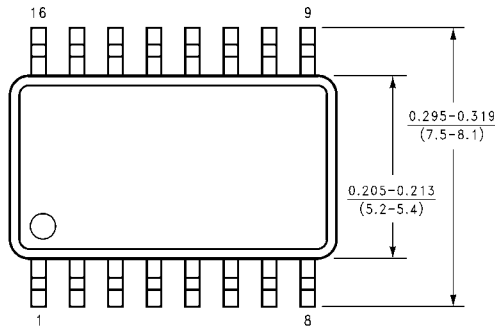
Absolute Maximum Ratings (Note 1)				Recommended Operating Conditions				
(Note 2)								
Supply Voltage ( $V_{CC}$ )		-0.5 to +7.0V		Min	Max	Units		
DC Input Voltage ( $V_{IN}$ )		-1.5 to $V_{CC}+1.5V$		2	6	V		
DC Output Voltage ( $V_{OUT}$ )		-0.5 to $V_{CC}+0.5V$		0	$V_{CC}$	V		
Clamp Diode Current ( $I_{IK}, I_{OK}$ )		$\pm 20$ mA						
DC Output Current, per pin ( $I_{OUT}$ )		$\pm 25$ mA						
DC $V_{CC}$ or GND Current, per pin ( $I_{CC}$ )		$\pm 50$ mA						
Storage Temperature Range ( $T_{STG}$ )		-65°C to +150°C						
Power Dissipation ( $P_D$ )								
(Note 3)		600 mW						
S.O. Package only		500 mW						
Lead Temperature ( $T_L$ )								
(Soldering 10 seconds)		260°C						
				<b>Note 1:</b> Absolute Maximum Ratings are those values beyond which damage to the device may occur. <b>Note 2:</b> Unless otherwise specified all voltages are referenced to ground. <b>Note 3:</b> Power Dissipation temperature derating — plastic "N" package: — 12 mW/°C from 65°C to 85°C				
DC Electrical Characteristics (Note 4)								
Symbol	Parameter	Conditions	$V_{CC}$	$T_A = 25^\circ\text{C}$		$T_A = -40$ to $85^\circ\text{C}$	$T_A = -55$ to $125^\circ\text{C}$	Units
				Typ	Guaranteed Limits			
$V_{IH}$	Minimum HIGH Level Input Voltage		2.0V		1.5	1.5	1.5	V
			4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
$V_{IL}$	Maximum LOW Level Input Voltage		2.0V		0.5	0.5	0.5	V
			4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
$V_{OH}$	Minimum HIGH Level Output Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 20 \mu\text{A}$	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 4.0$ mA $ I_{OUT}  \leq 5.2$ mA	4.5V	4.2	3.98	3.84	3.7	V
			6.0V	5.7	5.48	5.34	5.2	V
$V_{OL}$	Maximum LOW Level Output Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 20 \mu\text{A}$	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 4.0$ mA $ I_{OUT}  \leq 5.2$ mA	4.5V	0.2	0.26	0.33	0.4	V
			6.0V	0.2	0.26	0.33	0.4	V
$I_{IN}$	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		$\pm 0.1$	$\pm 1.0$	$\pm 1.0$	$\mu\text{A}$
$I_{CC}$	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu\text{A}$	6.0V		8.0	80	160	$\mu\text{A}$
<b>Note 4:</b> For a power supply of $5V \pm 10\%$ the worst case output voltages ( $V_{OH}$ , and $V_{OL}$ ) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case $V_{IH}$ and $V_{IL}$ occur at $V_{CC}=5.5V$ and 4.5V respectively. (The $V_{IH}$ value at 5.5V is 3.85V.) The worst case leakage current ( $I_{IN}$ , $I_{CC}$ , and $I_{OZ}$ ) occur for CMOS at the higher voltage and so the 6.0V values should be used.								

AC Electrical Characteristics								
(V <sub>CC</sub> = 5.0V, T <sub>A</sub> = 25°C, t <sub>r</sub> = t <sub>f</sub> = 6 ns, C <sub>L</sub> = 15 pF unless otherwise specified.)								
Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units			
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay Data to Output		18	32	ns			
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay Select to Output		20	38	ns			
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay Enable to Output		20	35	ns			
t <sub>PHL</sub>	Maximum Propagation Delay Clear to Output		17	27	ns			
t <sub>W</sub>	Minimum Enable Pulse Width		10	16	ns			
t <sub>W</sub>	Minimum Clear Pulse Width		10	16	ns			
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Time			500	ns			
t <sub>s</sub>	Minimum Setup Time Select or Data to Enable		15	20	ns			
t <sub>H</sub>	Minimum Hold Time Data or Address to Enable		-2	0	ns			
AC Electrical Characteristics								
t <sub>r</sub> = t <sub>f</sub> = 6 ns, C <sub>L</sub> = 50 pF, V <sub>CC</sub> = 2.0V – 6.0V								
Symbol	Parameter	Conditions	V <sub>CC</sub>	T <sub>A</sub> = 25°C		T <sub>A</sub> = -40 to 85°C	T <sub>A</sub> = -55 to 125°C	Units
				Typ	Guaranteed Limits			
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay Data to Output		2.0V	60	180	225	250	ns
			4.5V	19	37	46	52	ns
			6.0V	17	32	40	45	ns
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay Select to Output		2.0V	72	220	275	310	ns
			4.5V	21	43	54	60	ns
			6.0V	18	37	46	52	ns
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay Enable to Output		2.0V	65	200	250	280	ns
			4.5V	27	40	50	58	ns
			6.0V	23	35	44	50	ns
t <sub>PHL</sub>	Maximum Propagation Delay Clear to Output		2.0V	50	150	190	210	ns
			4.5V	18	31	39	44	ns
			6.0V	16	26	32	37	ns
t <sub>W</sub>	Minimum Pulse Width Clear or Enable		2.0V		80	100	120	ns
			4.5V		16	20	24	ns
			6.0V		14	18	20	ns
t <sub>s</sub>	Minimum Setup Time Address or Data to Enable		2.0V		100	125	150	ns
			4.5V		20	25	28	ns
			6.0V		15	19	25	ns
t <sub>H</sub>	Minimum Hold Time Address or Data to Enable		2.0V	-10	0	0	0	ns
			4.5V	-2	0	0	0	ns
			6.0V	-2	0	0	0	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Rise and Fall Time		2.0V	30	75	95	110	ns
			4.5V	8	15	19	22	ns
			6.0V	7	13	16	19	ns
C <sub>IN</sub>	Input Capacitance		5	10	10	10	pF	
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)	(per package)		80				pF
<b>Note 5:</b> C <sub>PD</sub> determines the no load dynamic power consumption, P <sub>D</sub> = C <sub>PD</sub> V <sub>CC</sub> <sup>2</sup> f + I <sub>CC</sub> V <sub>CC</sub> , and the no load dynamic current consumption, I <sub>S</sub> = C <sub>PD</sub> S V <sub>CC</sub> f + I <sub>CC</sub> .								

**Physical Dimensions** inches (millimeters) unless otherwise noted

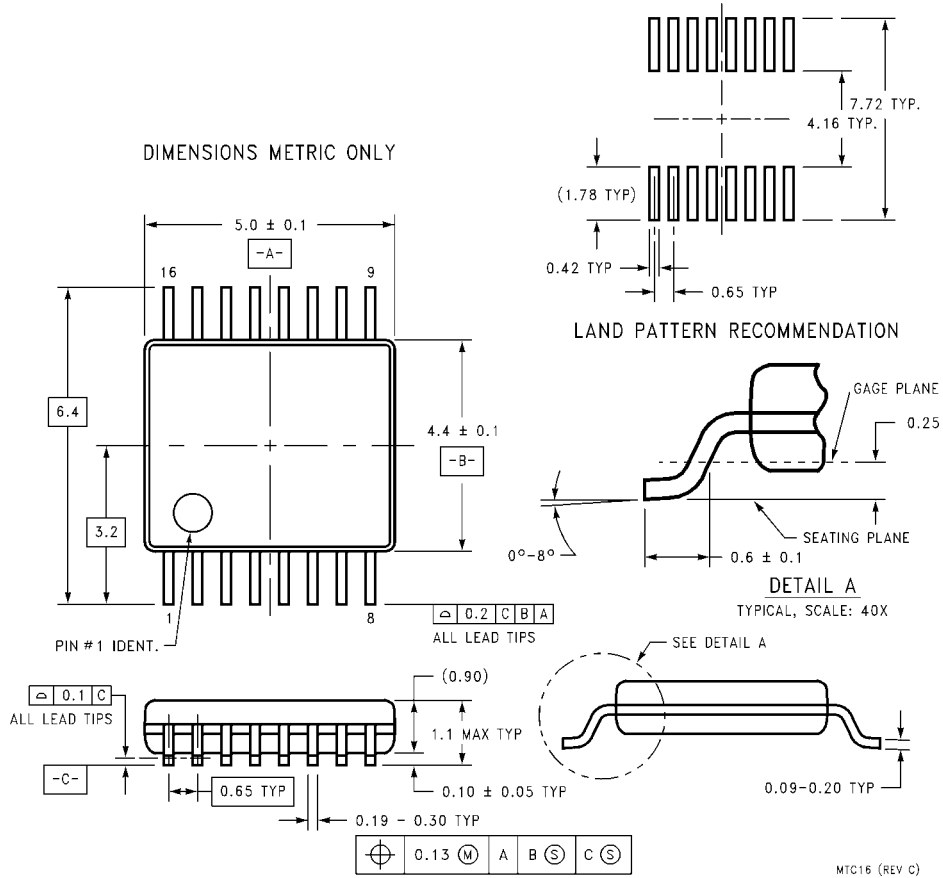


**16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow  
Package Number M16A**



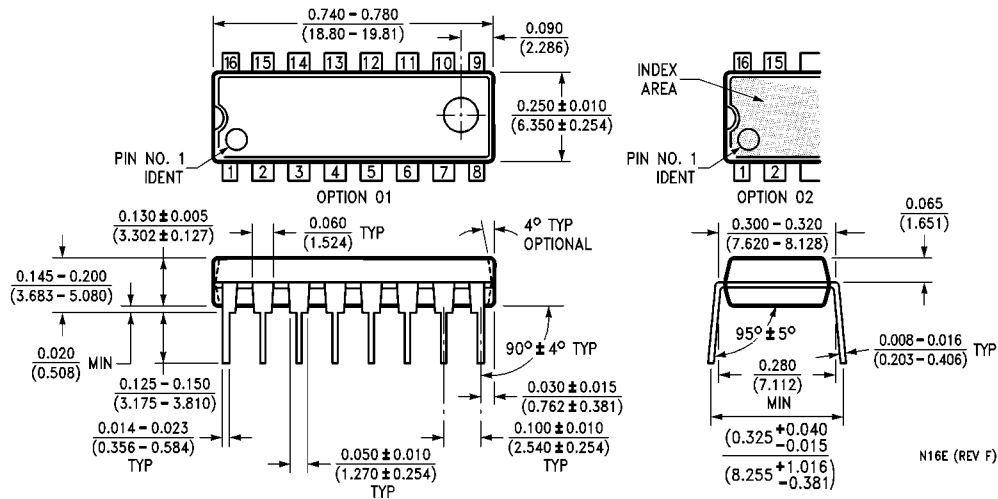
**16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide  
Package Number M16D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide  
Package Number MTC16**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N16E**

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